



ABSTRACT

An adhesive for electronic parts, which can be used for bonding and cured at a relatively low temperature and has sufficient heat resistance and reliability, and an adhesive tape for electronic parts, for which the above adhesive is adapted, the adhesive being a liquid adhesive obtained by dissolving an acrylonitrile-butadiene copolymer as Component (a), a phenolic resin as Component (b), a compound having at least 2 maleimide groups as Component (c) and a diamine compound of the general formula (1) specified in claim 1, and/or a polysiloxane compound terminating with an amino group at each terminal, having a weight average molecular weight of 200 to 7,000 and having the general formula specified in claim 1, as Component (d) in an organic solvent,

and in which the total amount of Components (b), (c) and (d) per 100 parts by weight of Component (a) is 10 to 900 parts by weight, the amount of Component (b) based on the total amount of Components (b), (c) and (d) is 10 to 90 % by weight, and the amount of amino groups of Component (d) per mole equivalent of the maleimide groups of Component (c) is 0.01 to 2.0 mole equivalents.